

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	30	٧
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Rectified Output Current	lo	2.0	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 5) Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{ heta JC}$ $R_{ heta JA}$	50 120	°C/W
Total Power Dissipation (Note 5)	P _{TOT}	0.84	W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

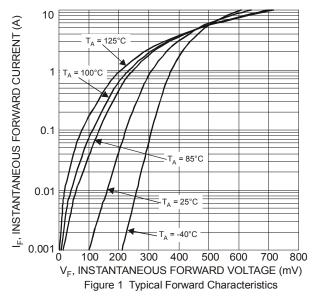
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

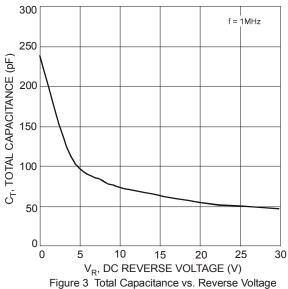
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)}$	30	_	_	V	I _R = 1.0 mA
Forward Voltage Drop	V _F	_	0.31 0.37 0.32	 0.42 	V	I _F = 1A, T _A = +25°C I _F = 2A, T _A = +25°C I _F = 2A, T _A = +100°C
Leakage Current (Note 6)	I _R	_	0.3 30	1.0 —	mA	VR = 30V, T _A = +25°C VR = 30V, T _A = +100°C
Total Capacitance	Ст	_	75	_	pF	VR = 10V, f = 1.0MHz

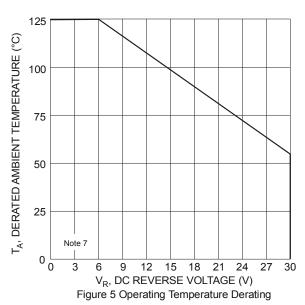
Notes:

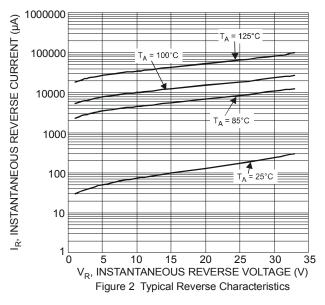
- 5. Device mounted on FR-4 substrate, 1" x 1", 2 oz, single-sided, PC boards with 0.1"*0.15" copper pad.
 6. Short duration pulse test used to minimize self-heating effect.
 7. Device mounted on FR-4 substrate, 1" x 1", 2 oz, single-sided, PC boards with minimum recommended pad per http://www.diodes.com/datasheets/ap02001.











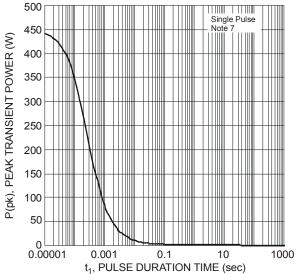
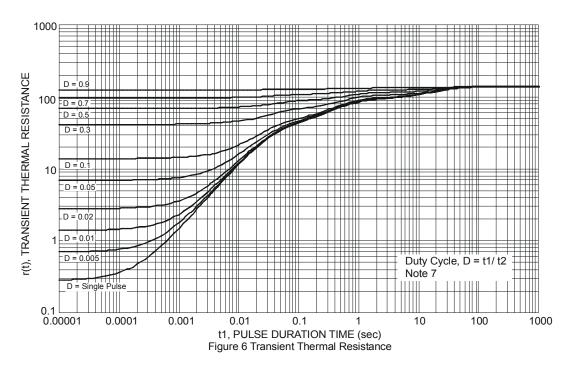


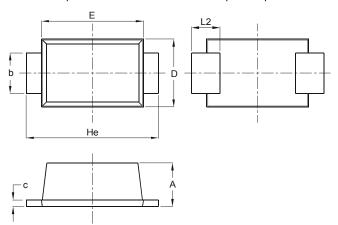
Figure 4 Single Pulse Maximum Power Dissipation





Package Outline Dimensions

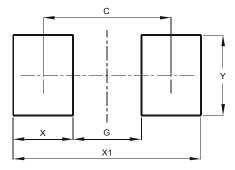
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOD123F				
Dim	Min	Max	Тур	
Α	0.81	1.15	-	
b	0.80	1.35	-	
С	0.05	0.30	ı	
D	1.70	1.90	1.80	
Е	2.60	2.80	2.70	
He	3.30	3.70	3.50	
L2	0.35	0.85	-	
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
С	2.86
G	1.52
X	1.34
X1	4.20
Υ	1.80



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